

# SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A DUAL 4-BIT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SDAS036D – APRIL 1982 – REVISED AUGUST 1995

- 3-State Buffer-Type Outputs Drive Bus Lines Directly
- Bus-Structured Pinout
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

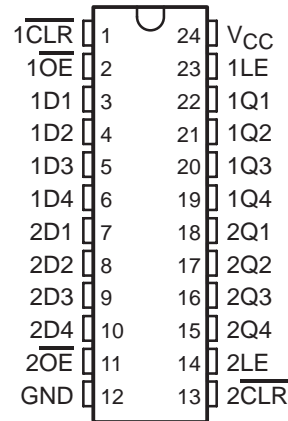
## description

These dual 4-bit D-type latches feature 3-state outputs designed specifically for bus driving. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

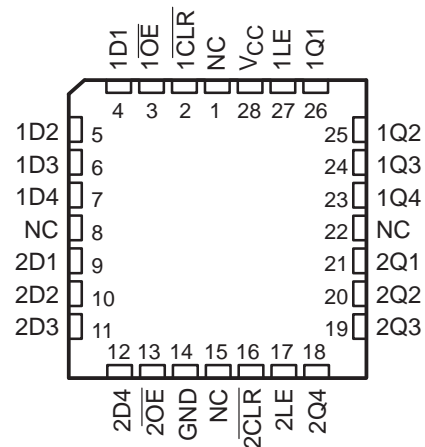
The dual 4-bit latches are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs in true form, according to the function table. When LE is low, the outputs are latched. When the clear (CLR) input goes low, the Q outputs go low independently of LE. The outputs are in the high-impedance state when the output-enable ( $\overline{OE}$ ) input is at a high logic level.

The SN54ALS873B and SN54AS873A are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74ALS873B and SN74AS873A are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54ALS873B, SN54AS873A . . . JT PACKAGE  
SN74ALS873B, SN74AS873A . . . DW OR NT PACKAGE  
(TOP VIEW)



SN54ALS873B, SN54AS873A . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE  
(each latch)

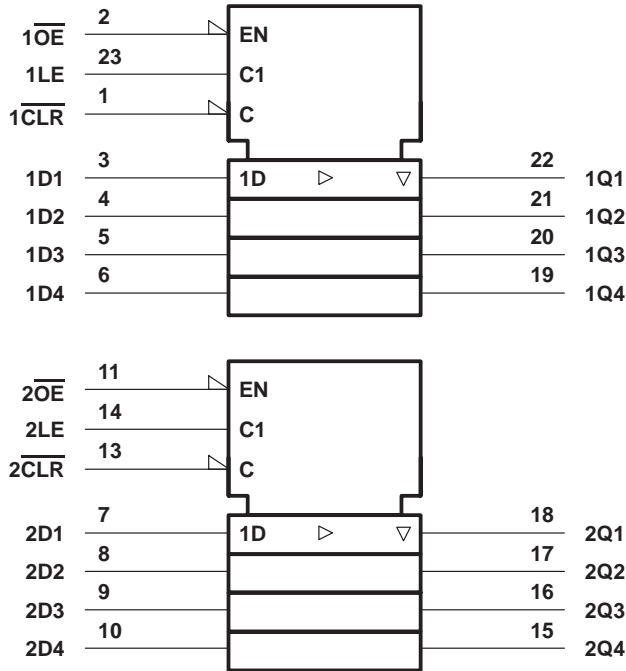
INPUTS				OUTPUT Q
$\overline{OE}$	$\overline{CLR}$	LE	D	
L	L	X	X	L
L	H	H	H	H
L	H	H	L	L
L	H	L	X	$Q_0$
H	X	X	X	Z

# SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A

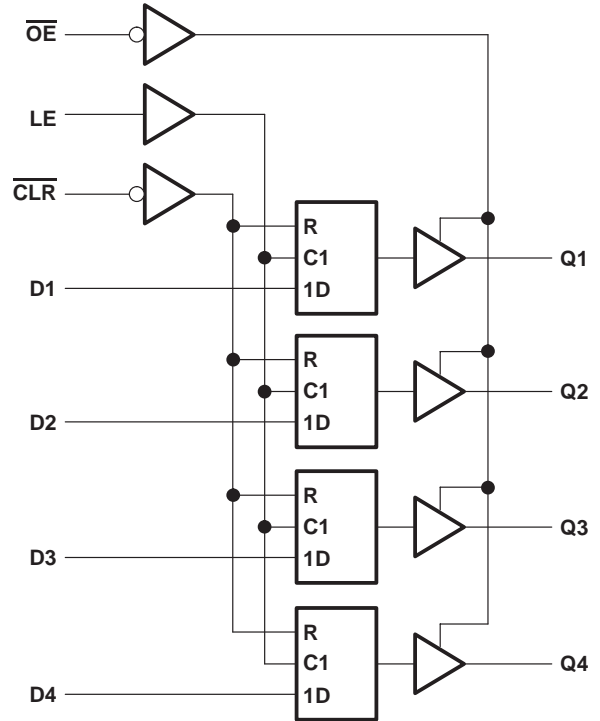
## DUAL 4-BIT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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### logic symbol†



### logic diagram (each quad latch, positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the DW, JT, and NT packages.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, $V_{CC}$	7 V
Input voltage, $V_I$	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, $T_A$ : SN54ALS873B	-55°C to 125°C
SN74ALS873B	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

	SN54ALS873B			SN74ALS873B			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$ Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$ High-level input voltage	2			2			V
$V_{IL}$ Low-level input voltage			0.7			0.8	V
$I_{OH}$ High-level output current			-1			-2.6	mA
$I_{OL}$ Low-level output current			12			24	mA
$T_A$ Operating free-air temperature	-55		125	0		70	°C



# SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A DUAL 4-BIT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALS873B		SN74ALS873B		UNIT
			MIN	TYP†	MAX	MIN	
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$	-1.2		-1.2		V
$V_{OH}$	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ ,	$I_{OH} = -0.4\text{ mA}$	$V_{CC} - 2$		$V_{CC} - 2$		V
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -1\text{ mA}$	2.4	3.3	2.4	3.2	
$V_{OL}$	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 12\text{ mA}$	0.25	0.4	0.25	0.4	V
		$I_{OL} = 24\text{ mA}$			0.35	0.5	
$I_{OZH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.7\text{ V}$	20		20		$\mu\text{A}$
$I_{OZL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0.4\text{ V}$	-20		-20		$\mu\text{A}$
$I_I$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 7\text{ V}$	0.1		0.1		mA
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 2.7\text{ V}$	20		20		$\mu\text{A}$
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 0.4\text{ V}$	-0.2		-0.2		mA
$I_{O\ddagger}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.25\text{ V}$	-20	-112	-30	-112	mA
$I_{CC}$	$V_{CC} = 5.5\text{ V}$	Outputs high	11	21	11	21	mA
		Outputs low	16	29	16	29	
		Outputs disabled	20	31	20	31	

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54ALS873B		SN74ALS873B		UNIT
		MIN	MAX	MIN	MAX	
$t_w$	Pulse duration	$\overline{\text{CLR}}$ low	15	15	ns	
		LE high	10	10		
$t_{su}$	Setup time, data before LE↓	10		10		ns
$t_h$	Hold time, data after LE↓	7		7		ns



# SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A

## DUAL 4-BIT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>1</sub> = 500 Ω, R <sub>2</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			SN54ALS873B		SN74ALS873B		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	D	Q	2	23	2	14	ns
t <sub>PHL</sub>			2	17	2	14	
t <sub>PLH</sub>	LE	Q	8	31	8	22	ns
t <sub>PHL</sub>			8	26	8	21	
t <sub>PHL</sub>	CLR	Q	6	27	6	20	ns
t <sub>PZH</sub>	OE	Q	4	24	4	18	ns
t <sub>PZL</sub>			4	23	4	18	
t <sub>PHZ</sub>	OE	Q	2	12	2	10	ns
t <sub>PLZ</sub>			2	30	2	15	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T <sub>A</sub> : SN54AS873A	-55°C to 125°C
SN74AS873A	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

	SN54AS873A			SN74AS873A			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.8			0.8	V
I <sub>OH</sub> High-level output current			-12			-15	mA
I <sub>OL</sub> Low-level output current			32			48	mA
T <sub>A</sub> Operating free-air temperature	-55		125	0		70	°C



# SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A DUAL 4-BIT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54AS873A			SN74AS873A			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$	-1.2			-1.2			V
$V_{OH}$	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ ,	$I_{OH} = -2\text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -12\text{ mA}$	2.4	3.2					
$V_{OL}$	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 32\text{ mA}$	0.25		0.5				V
		$I_{OL} = 48\text{ mA}$			0.35		0.5		
$I_{OZH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.7\text{ V}$	50			50			$\mu\text{A}$
$I_{OZL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0.4\text{ V}$	-50			-50			$\mu\text{A}$
$I_I$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 7\text{ V}$	0.1			0.1			mA
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 2.7\text{ V}$	20			20			$\mu\text{A}$
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 0.4\text{ V}$	-0.5			-0.5			mA
$I_O^\ddagger$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.25\text{ V}$	-30	-112		-30	-112		mA
$I_{CC}$	$V_{CC} = 5.5\text{ V}$	Outputs high	68	110		68	110		mA
		Outputs low	67	109		67	109		
		Outputs disabled	80	129		80	129		

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54AS873A		SN74AS873A		UNIT
		MIN	MAX	MIN	MAX	
$t_w^*$	Pulse duration	CLR low		5	5	ns
		LE high		6	5	
$t_{su}^*$	Setup time, data before LE↓	2		2	ns	
$t_h^*$	Hold time, data after LE↓	4.5		4.5	ns	

\* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



**SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A**  
**DUAL 4-BIT D-TYPE LATCHES**  
**WITH 3-STATE OUTPUTS**

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**switching characteristics (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>1</sub> = 500 Ω, R <sub>2</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			SN54AS873A		SN74AS873A		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	D	Q	3	12.5	3	9.5	ns
t <sub>PHL</sub>			3	8.5	3	7.5	
t <sub>PLH</sub>	LE	Q	6	15.5	6	13	ns
t <sub>PHL</sub>			4	9	4	7.5	
t <sub>PHL</sub>	$\overline{\text{CLR}}$	Q	3	10.5	3	9	ns
t <sub>PZH</sub>	$\overline{\text{OE}}$	Q	2	8	2	6.5	ns
t <sub>PZL</sub>			4	11	4	10.5	
t <sub>PHZ</sub>	$\overline{\text{OE}}$	Q	2	8	2	7.5	ns
t <sub>PLZ</sub>			2	8.5	2	7.5	

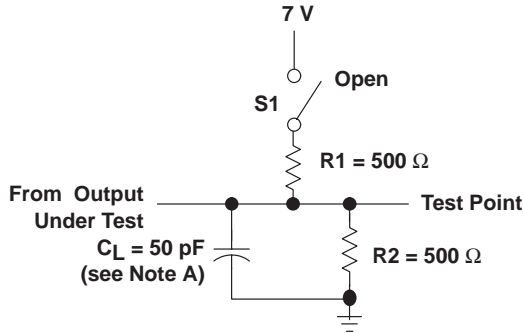
† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



# SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A DUAL 4-BIT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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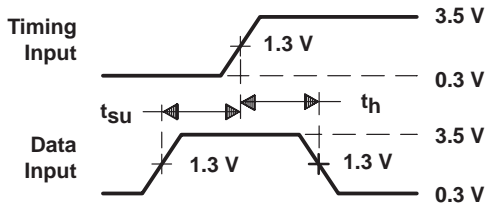
## PARAMETER MEASUREMENT INFORMATION



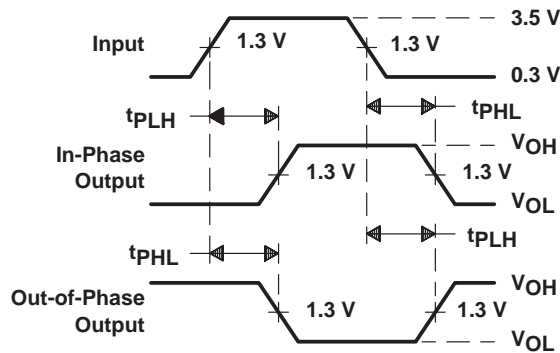
LOAD CIRCUIT FOR 3-STATE OUTPUTS

SWITCH POSITION TABLE

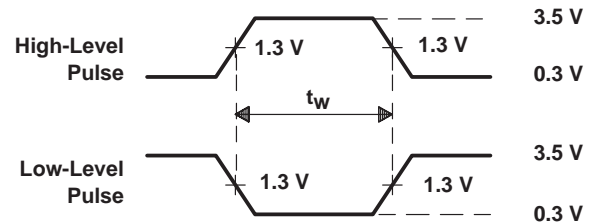
TEST	S1
$t_{PLH}$	Open
$t_{PHL}$	Open
$t_{PZH}$	Open
$t_{PZL}$	Closed
$t_{PHZ}$	Open
$t_{PLZ}$	Closed



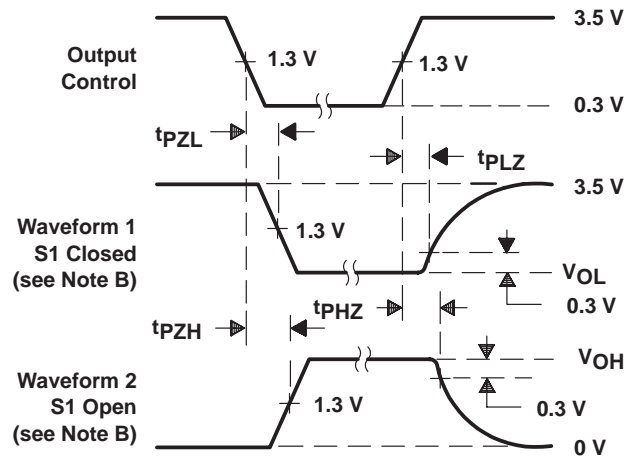
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2$  ns,  $t_f \leq 2$  ns.  
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
84032013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84032013A SNJ54ALS 873BFK	<a href="#">Samples</a>
8403201KA	OBSOLETE	CFP	W	24		TBD	Call TI	Call TI	-55 to 125		
8403201LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403201LA SNJ54ALS873BJT	<a href="#">Samples</a>
SN74ALS873BDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	<a href="#">Samples</a>
SN74ALS873BDWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	<a href="#">Samples</a>
SN74ALS873BDWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	<a href="#">Samples</a>
SN74ALS873BDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	<a href="#">Samples</a>
SN74ALS873BDWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	<a href="#">Samples</a>
SN74ALS873BDWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	<a href="#">Samples</a>
SN74ALS873BNT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS873BNT	<a href="#">Samples</a>
SN74ALS873BNT3	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SN74ALS873BNTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS873BNT	<a href="#">Samples</a>
SN74AS873ADW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74AS873ADWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74AS873ANT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SNJ54ALS873BFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84032013A SNJ54ALS 873BFK	<a href="#">Samples</a>
SNJ54ALS873BJT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403201LA SNJ54ALS873BJT	<a href="#">Samples</a>
SNJ54AS873AFK	OBSOLETE	LCCC	FK	28		TBD	Call TI	Call TI	-55 to 125		
SNJ54AS873AJT	OBSOLETE	CDIP	JT	24		TBD	Call TI	Call TI	-55 to 125		



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54AS873AW	OBSOLETE	CFP	W	24		TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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**OTHER QUALIFIED VERSIONS OF SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A :**

● Catalog: [SN74ALS873B](#), [SN74AS873A](#)

● Military: [SN54ALS873B](#), [SN54AS873A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS873BDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS873BDWR	SOIC	DW	24	2000	367.0	367.0	45.0

JT (R-GDIP-T\*\*)

CERAMIC DUAL-IN-LINE

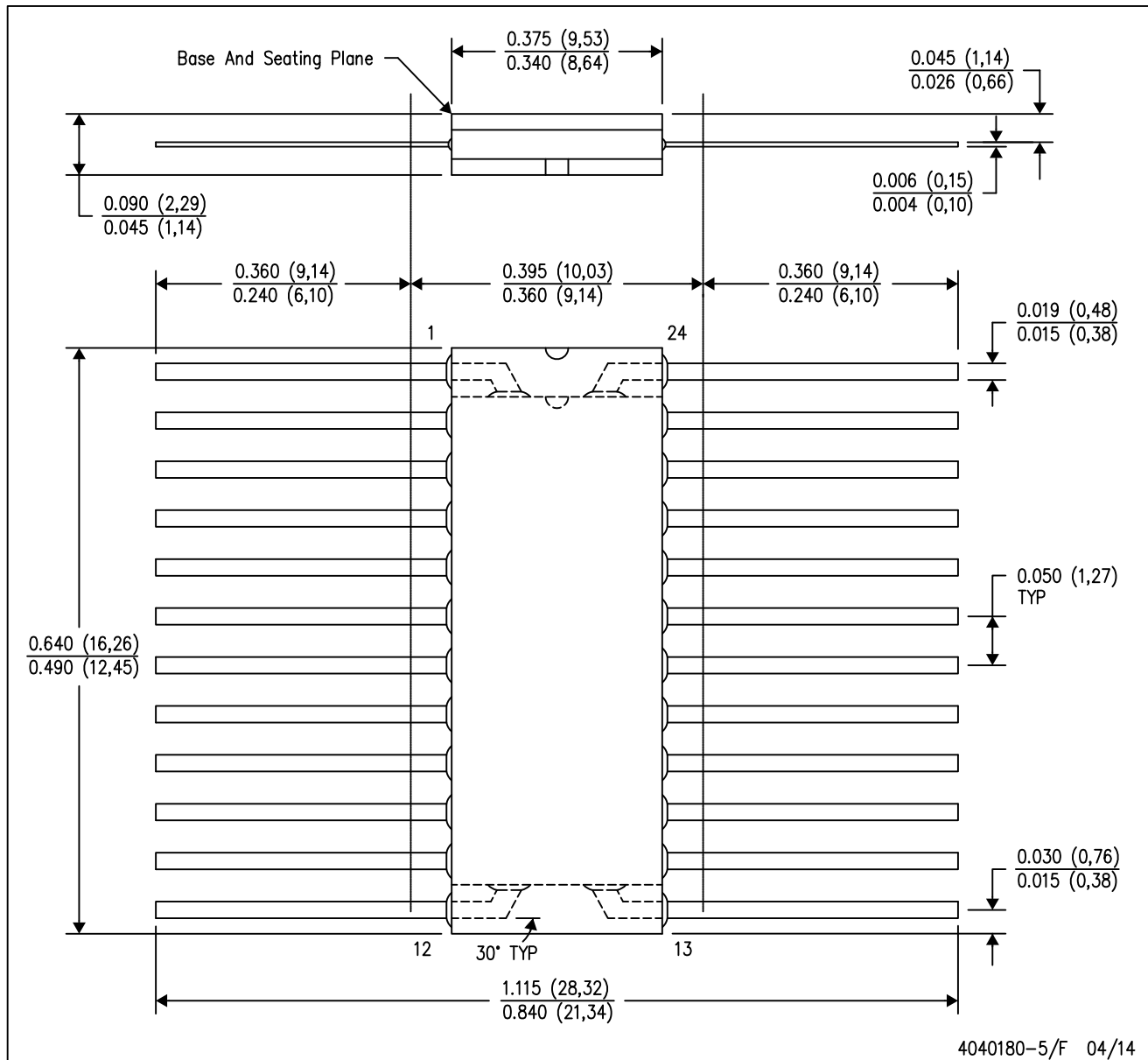
24 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification.  
 E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

W (R-GDFP-F24)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

# MECHANICAL DATA

NT (R-PDIP-T\*\*) 24 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

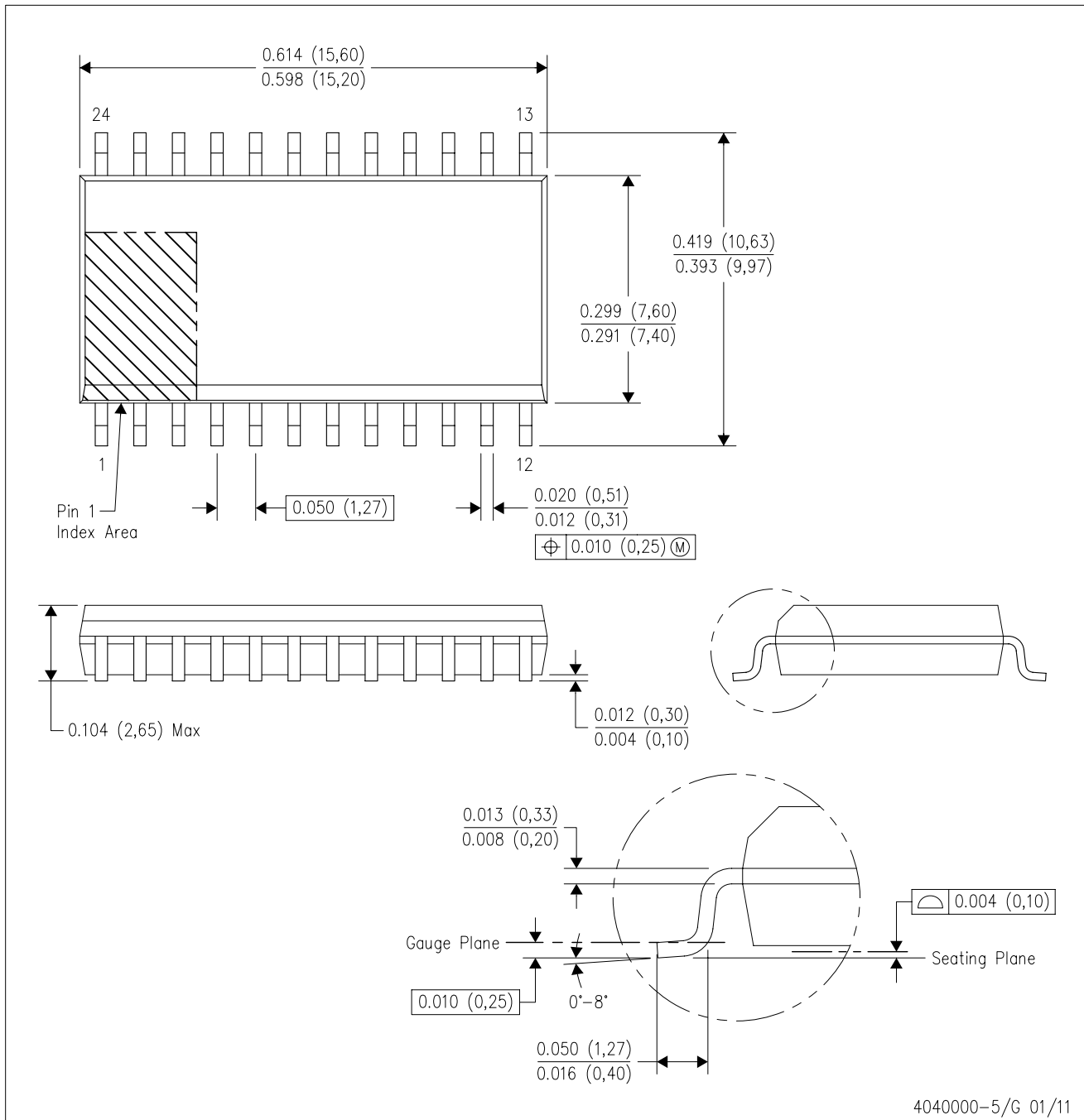


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.

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